SURFACE Mount Super RECOVERY RECTIFIERS

Forward Current-2A

Reverse Voltage-50V to 600V

FEATURES

- For surface mounted applications
- Glass passivated chip junction
- ◆ Low profile package
- Superfast reverse recovery time
- ◆ Lead free in comply with EU RoHS 2011/65/EU directives

PINING

PIN	DESCRIPTION
1	Cathode
2	Anode



MECHANICAL DATA

Case: SMB molded plastic body

◆ Terminals: Solderable per MIL-STD- 750, Method 2026

Weight: Approximated 0.055 g/0.002 oz

MAXIMUM RATINGS AND ELECTRICAL CHARACTERISTICS

Ratings at 25°C ambient temperature unless otherwise specified.

Single phase half-wave 60 Hz, resistive or inductive load, for capacitive load current derating by 20 %.

PARAMETER	SYMBOL	ES2AB -AT	ES2BB -AT	ES2CB -AT	ES2DB -AT	ES2EB -AT	ES2GB -AT	ES2JB -AT	UNIT
Maximum Repetitive Peak Reverse Voltage	V _{RRM}	50	100	150	200	300	400	600	V
Maximum RMS Voltage	V _{RMS}	35	70	105	140	210	280	420	V
Maximum DC Blocking Voltage	V _{DC}	50	100	150	200	300	400	600	V
Maximum Average Forward Rectified Current at T _C =125°C	I _{F(AV)}	2					Α		
Peak Forward Surge Current(Note1)	I _{FSM}	60						Α	
Maximum Forward Voltage at 2.0 A	V _F	1.0 1.25 1.68					V		
Maximum DC Reverse Current at Rated DC Blocking Voltage T _A =25°C T _A =125°C	I _R	5 100					uA		
Typical Junction <mark>Capaci</mark> tance at V _R =4V,f=1MHZ	Cj	40					pF		
Maximum Reverse Recovery Time (Note1)	T _{rr}	35					nS		
Typical Thermal Resistance (Note2)	R _{0JA} R _{0JC}	60 20					°C/W		
Operating and Storage Temperature Range	T _J ,T _{STG}	-55 to +150					°C		

Notes: 1. Measured with I_F =0.5A, I_R =1A, I_{rr} =0.25A.

2. P.C.B. mounted with 2.0" X 2.0" (5cm X 5 cm) copper pad areas.



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RATINGS AND CHARACTERISTIC CURVES

Fig.1 Reverse Recovery Time Characteristic And Test Circuit Diagram

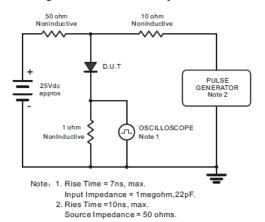


Fig. 2 Maximum Average Forward Current Rating

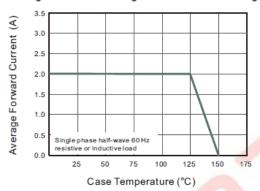
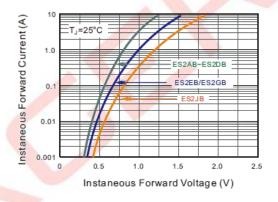
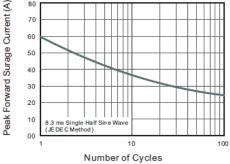


Fig.4 Typical Forward Characteristics



Forward Surage Current 70 60

Fig.6 Maximum Non-Repetitive Peak



+0.5 0 -0.25 -1.0 Set time Base for 10ns/div

Fig.3 Typical Reverse Characteristics

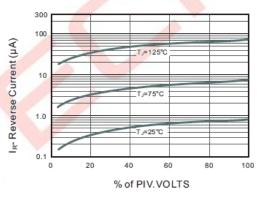
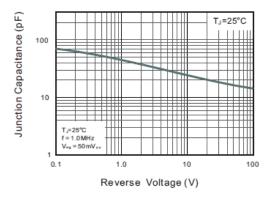


Fig.5 Typical Junction Capacitance





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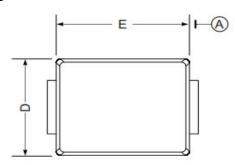
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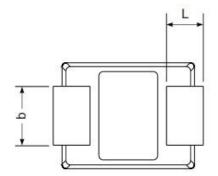
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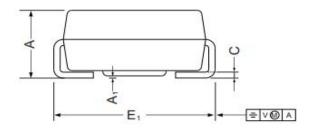
ES2AB-AT THRU ES2JB-AT

PACKAGE OUTLINE

SMB





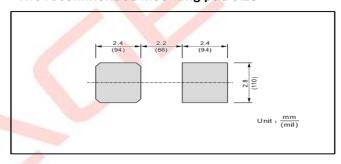


Dimensions in milimeters

SMB mechanical data

UNIT		Α	E	D	E ₁	A ₁	L	С	b
mm	max	2.44	4.70	3.94	5.59	0.20	1.5	0.305	2.2
	min	2.13	4.06	3.3	5.08	0.05	8.0	0.152	1.9
mil	max	96	185	155	220	7.9	59	12	87
	min	84	160	130	200	2.0	32	6	75

The recommended mounting pad size





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